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## Winbond gets \$92.9 million for fire damage to fab

HSINCHU, Taiwan -- Winbond Electronics Corp. here today announced that it has reached a final settlement with its insurance companies over a fire that nearly destroyed its initial 8-inch wafer fab last October.

Hsinchu-based Winbond, one of Taiwan's largest chip makers, today said it received a settlement of about \$92.9 million from the insurance companies, which will cover the cost of the damaged equipment in the fab.

Earlier this year, Winbond received another \$129 million from the insurance companies that covers the costs of the damaged building.

Last October, an unexplained fire at Winbond's newly completed Fab III caused extensive damage and production delays. Winbond officials insist that Fab III will be refurbished and running in 1998 or 1999.

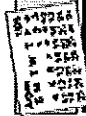
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